DERWENT-ACC-NO: 2002-478780

DERWENT-WEEK: 200501

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TITLE: **Metal-insulator-metal capacitor** for use in integrated
electrically
                        circuits, comprises conductive layers

                        coupled by etch-stop layers

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 Title - TIX (1):
    Metal-insulator-metal capacitor for use in integrated circuits,
comprises
conductive layers electrically coupled by etch-stop layers

 PF Application Date - PFAD (1):
    20001003

 PF Application Date - PFAD (3):
    20001003

 Equivalent Abstract Text - ABEQ (1):
    NOVELTY - A **metal-insulator-metal capacitor** comprises a first
conductive
layer (201) electrically coupled with an etch-stop layer, and a
second
conductive layer electrically coupled with the etch-stop layer. The
etch-stop
layer has a preselected dielectric constant and a predetermined
geometry.

 Equivalent Abstract Text - ABEQ (3):
    USE - As metal-insulator-metal **(MIM) capacitor** in integrated
circuits.

 Equivalent Abstract Text - ABEQ (5):
    DESCRIPTION OF DRAWING(S) - The figure shows a color
representation of a
composite plan view of a multilayer interdigitated **MIM capacitor**.

 Inventor Name - INNM (1):
    TSAU, L

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	2475	(metal-insulator-Metal or (metal near insulat$6 near metal) or MIM) near2 capacitor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:41
2	L2	50327	"etch stop" or "etch stopper" or ((stop$4 or barrier) near4 insulat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:38
3	L3	508	L1 and L2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:38
4	L4	277	L3 and (copper or Cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:39
5	L5	56	L4 and ((@ad<"20010104") or (@rlad<"20010104"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:39

	L #	Hits	Search Text	DBs	Time Stamp
6	L6	3892	Broadcom.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:39
7	L7	19	6 and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:39
8	L8	8	7 and (copper or Cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:39
9	L9	1	8 and ((@ad<"20010104") or (@rlad<"20010104"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:42
10	L10	21	6 and (MIM or metal-insulator-metal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:41

	L #	Hits	Search Text	DBs	Time Stamp
11	L11	10	10 and ((@ad<"20010104") or (@rlad<"20010104"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:44
12	L12	20	6 and MIM	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:43
13	L13	18	6 and (MIM near capacitor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:43
14	L14	8	13 and (Cu or copper)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:44
15	L15	1	14 and ((@ad<"20010104") or (@rlad<"20010104"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:46

	L #	Hits	Search Text	DBs	Time Stamp
16	L16	223	Tsau.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:45
17	L17	12	16 and (((metal-insulator-metal) or MIM) near capacitor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:46
18	L18	4	17 and ((@ad<"20010104") or (@rlad<"20010104"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/06/15 15:46